

- 適用於較高電流設計板材之符合新一代環保要求之電解銅箔。

MW-G heavy copper foil comply with environment regulation is suitable for use in high current board design.

- 較低的粗糙度特性具優越的蝕刻性。

Good bonding strength./ Excellent heat resistance./ Good etchability.

- 銅箔穩定的量產能力, 可充分供應客戶需求。

Our plant has stable capacity for MW-G to fulfill customer requirements.

用途/Application

- 汽車板
/Automotive board
- 與電源供應器
/Power supply unit
- 太陽能板
/ Solar panel

結構/Composition



生產地點/Production Site

- 台灣 / Taiwan
- 馬來西亞 / Malaysia

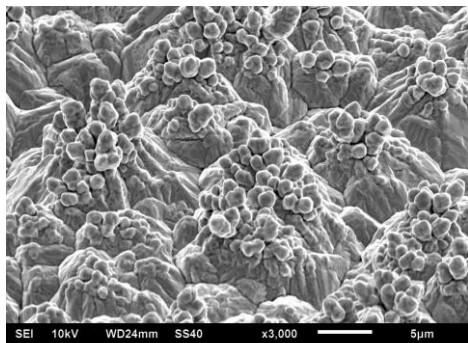
特性代表值/Representative data

	μm	Rz (μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)
MW-G	105	13.0	300	15	>3.0
	140	14.0	300	15	>3.0
	175	15.0	300	15	>3.0
	210	15.0	300	15	>3.0

※上述表列為代表性數據非保證值。

This is representative data, not guarantee.

處理面/Laminate side



阻劑面/ Resist side

